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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Where Patent Application of:)

Brian Eric LINDHOLM et al.)

Examiner: M. DATSKOVSKY

Serial No.: 09/683,496)

Art Unit: 2835

Filed: January 9, 2002)

For: "METHOD AND APPARATUS FOR COOLING ELECTRICAL FUSES"

Under Secretary of Commerce for Intellectual Property and
Director of the United States Patent and Trademark Office
Washington, D.C. 20231

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SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Sir:

In accordance with 37 C.F.R. §§ 1.56, 1.97, and 1.98, Applicant respectfully requests consideration of the references listed on the attached Form PTO-1449. A copy of the references listed are also enclosed.

Applicant respectfully requests that the Examiner consider the references cited on the PTO-1449 and that the Examiner indicate that the references have been considered in this application by returning a copy of the Form PTO-1449 with the Examiner's initials in the left column per MPEP 609.

Applicant also cites pending U.S. patent application on the Form PTO-1449 (copy enclosed). The Examiner is referred to such patent application, and the art cited therein, for the examination of the present application.

This Supplemental Information Disclosure Statement is being submitted after the mailing of a non-final Office Action, but is believed to be prior to a final Office Action or a Notice of

Allowance. Pursuant to 37 C.F.R. § 1.97(c)(2), a check in the amount of \$180.00 as set forth in § 1.17(p) is enclosed.

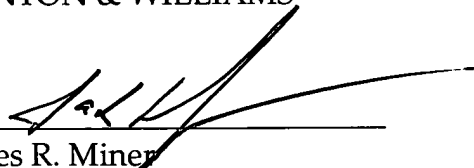
In the event any variance exists between the amount enclosed and the Patent Office charges, please charge or credit any difference to the undersigned's Deposit Account No. 50-0206.

Respectfully submitted,

HUNTON & WILLIAMS

Date: June 16, 2003

By:



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FORM PTO-1449
(REV. 7-80)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.:
57761.000185SERIAL NO.:
09/683,496INVENTOR'S NAME:
Eric LINDHOLM, et al.EXAMINER:
M. DatskovskyFILING DATE:
January 9, 2002GROUP
2835

LIST OF MATERIALS CITED BY APPLICANT

(Use several sheets if necessary)

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER							DATE	NAME	CLASS	SUB CLASS	FILING DATE
	A	6	0	1	8	4	5	9	01/25/00	Carlson, et al.			
	B	6	1	3	1	6	4	4	10/17/00	Kohara, et al.			
	C	6	1	3	1	6	5	0	10/17/00	North et al.			
	D	5	9	8	7	8	9	3	11/23/99	Schulz-Harder, et al.			
	E	6	0	1	4	3	1	2	01/11/00	Schulz-Harder et al.			
	F	5	8	4	1	6	3	4	11/24/98	Visser			
	G	5	2	0	5	3	5	3	04/27/93	Willemsen, et al.			
	H												
	I												
	J												
	K												
	L												
	M												
	N												
	O												

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER							DATE	COUNTRY	CLASS	SUB CLASS	TRANS LATION	
													YES	NO

OTHER MATERIALS (Including Author, Title, Date, Pertinent Pages, Etc.)

U.S. Patent Application 10/063,985, filed May 31, 2002 and the references cited therein.

"Fluid-Cooled DBC Substrates," by J. Schulz-Harder, K. Exel, and A. Meyer

"Direct Bond Copper Substrates," from Thermalloy

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

